

Electronic packaging and interconnection handbook

McGraw-Hill - Printed Circuit Board Materials Handbook Electronic Packaging And Interconnection PDF Book



Description: -

- Arab countries -- Politics and government.
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- Electronic packaging -- Handbooks, manuals, etc. Electronic packaging and interconnection handbook
- Electronic packaging and interconnection handbook
- Notes: Includes bibliographical references and index.
- This edition was published in 1991



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Electronic Packaging and Interconnection Handbook, 4th edition edited by Charles A. Harper

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Electronic Packaging and Interconnection Handbook 4/E

Electronic packaging and interconnection handbook (2005 edition)

The item may be missing the original packaging such as the original box or bag or tags or in the original packaging but not sealed. Packaging of High Speed and Microwave Electronic Systems. Of interest to mechanical and electrical engineers, chemists, physicists, and materials scientists in all areas of the electronic packaging industry, the book takes a unique interdisciplinary approach to the field, allowing specialists in one area to understand the needs and responsibilities of others.

PRINTED CIRCUIT BOARD MATERIALS HANDBOOK ELECTRONIC PACKAGING AND INTERCONNECTION

Written by a team of experts from around the globe, this remarkable volume covers all aspects of electronic packaging, including: Materials Thermal Management Shock, Vibration, and Operational Stress Management Connector and Interconnection Technologies Soldering and Cleaning Technologies Single Chip Packaging and Ball Grid Arrays Surface Mount Technology Hybrid and Multichip Modules Chip-Scale, Flip-Chip, and Direct-Chip Attachment Rigid and Flexible Printed-Wiring Boards Packaging High-Speed and Microwave Systems Packaging High-Voltage Systems Packaging of MEMs Systems Packaging of Optoelectronic Systems CONTRIBUTORSPREFACE Chapter 1: Plastics, Elastomers, and Composites Chapter 2: Adhesives, Underfills, and Coatings Chapter 3: Thermal Management Chapter 4: Connector and Interconnection Technology Chapter 5: Solder Technologies for Electronic Packaging and Assembly Chapter 6: Packaging and Interconnection of Integrated Circuits Chapter 7: Hybrid Microelectronics and Multichip Modules Chapter 8: Chip Scale, Flip Chip, and Advanced Chip Packaging Technologies Chapter 9: Rigid and Flexible Printed Circuit Board Technology Chapter 10: Packaging of High-Speed and Microwave Electronic Systems INDEX Intended for electronic engineers, this handbook describes the various approaches to handling thermal management issues in electronic packaging, the function and structure of connectors, and the properties of solder technologies for electronic assembly. This thoroughly revised and expanded Fourth Edition adds new information on key MEMs; optoelectronic, single-chip, and high-speed technologies; and updates important chapters on ball grid array and flip chip technologies. April 30th 1997 printed circuit board materials handbook electronic packaging and interconnection martin w jawitz on amazon com free shipping on qualifying offers select pcb 6 7 materials for top performing boards lt b gt from weaving glass fiber mats to testing finished boards.

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